

## Molding Type Module IGBT, 2 in 1 Package, 1200 V and 100 A



Double INT-A-PAK

### FEATURES

- NPT IGBT technology
- 10  $\mu$ s short circuit capability
- Low switching losses
- Rugged with ultrafast performance
- $V_{CE(on)}$  with positive temperature coefficient
- Low inductance case
- Fast and soft reverse recovery antiparallel FWD
- Isolated copper baseplate using DCB (Direct Copper Bonding) technology
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
COMPLIANT

| PRODUCT SUMMARY  |                  |
|--|------------------|
| $V_{CES}$  | 1200 V           |
| $I_C$ at $T_C = 80\text{ }^\circ\text{C}$                                      | 100 A            |
| $V_{CE(on)}$ (typical)<br>at $I_C = 100\text{ A}$ , $25\text{ }^\circ\text{C}$ | 3.10 V           |
| Package  | Double INT-A-PAK |
| Circuit  | Half bridge      |

### TYPICAL APPLICATIONS

- Switching mode power supplies
- Inductive heating
- Electronic welder

### DESCRIPTION

Vishay's IGBT power module provides ultrafast switching speed as well as short circuit ruggedness. It is designed for applications such as electronic welders and inductive heating.

| ABSOLUTE MAXIMUM RATINGS ( $T_C = 25\text{ }^\circ\text{C}$ unless otherwise noted) |                |   |          |       |
|---|----------------|---|----------|-------|
| PARAMETER   | SYMBOL         | TEST CONDITIONS                         | MAX.     | UNITS |
| Collector to emitter voltage  | $V_{CES}$      |   | 1200     | V     |
| Gate to emitter voltage   | $V_{GES}$      |   | $\pm 20$ |       |
| Collector current   | $I_C$          | $T_C = 25\text{ }^\circ\text{C}$        | 200      | A     |
|   |                | $T_C = 80\text{ }^\circ\text{C}$        | 100      |       |
| Pulsed collector current  | $I_{CM}^{(1)}$ | $t_p = 1\text{ ms}$                     | 200      |       |
| Diode continuous forward current  | $I_F$          |   | 100      |       |
| Diode maximum forward current   | $I_{FM}^{(1)}$ |   | 200      |       |
| Maximum power dissipation   | $P_D$          | $T_J = 150\text{ }^\circ\text{C}$       | 1136     | W     |
| Isolation voltage   | $V_{ISOL}$     | $f = 50\text{ Hz}$ , $t = 1\text{ min}$ | 2500     | V     |

#### Note

<sup>(1)</sup> Repetitive rating: Pulse width limited by maximum junction temperature.



| IGBT ELECTRICAL SPECIFICATIONS ( $T_C = 25\text{ }^\circ\text{C}$ unless otherwise noted) |               |   |      |      |      |       |
|---|---------------|---|------|------|------|-------|
| PARAMETER   | SYMBOL        | TEST CONDITIONS   | MIN. | TYP. | MAX. | UNITS |
| Collector to emitter breakdown voltage  | $V_{(BR)CES}$ | $T_J = 25\text{ }^\circ\text{C}$  | 1200 | -    | -    | V     |
| Collector to emitter voltage  | $V_{CE(on)}$  | $V_{GE} = 15\text{ V}, I_C = 100\text{ A}, T_J = 25\text{ }^\circ\text{C}$  | -    | 3.10 | 3.60 |       |
|   |               | $V_{GE} = 15\text{ V}, I_C = 100\text{ A}, T_J = 125\text{ }^\circ\text{C}$ | -    | 3.45 | -    |       |
| Gate to emitter threshold voltage   | $V_{GE(th)}$  | $V_{CE} = V_{GE}, I_C = 1\text{ mA}, T_J = 25\text{ }^\circ\text{C}$        | 4.4  | 4.9  | 6.0  |       |
| Zero gate voltage collector current   | $I_{CES}$     | $V_{CE} = V_{CES}, V_{GE} = 0\text{ V}, T_J = 25\text{ }^\circ\text{C}$     | -    | -    | 5.0  | mA    |
| Gate to emitter leakage current   | $I_{GES}$     | $V_{GE} = V_{GES}, V_{CE} = 0\text{ V}, T_J = 25\text{ }^\circ\text{C}$     | -    | -    | 400  | nA    |

| SWITCHING CHARACTERISTICS                |               |   |      |      |      |               |
|--|---------------|---|------|------|------|---------------|
| PARAMETER                                | SYMBOL        | TEST CONDITIONS   | MIN. | TYP. | MAX. | UNITS         |
| Turn-on delay time                       | $t_{d(on)}$   | $V_{CC} = 600\text{ V}, I_C = 100\text{ A}, R_g = 5.6\text{ }\Omega,$<br>$V_{GE} = \pm 15\text{ V}, L = 200\text{ nH}, T_J = 25\text{ }^\circ\text{C}$  | -    | 300  | -    | ns            |
| Rise time                                | $t_r$         |   | -    | 64   | -    |               |
| Turn-off delay time                      | $t_{d(off)}$  |   | -    | 340  | -    |               |
| Fall time                                | $t_f$         |   | -    | 105  | -    |               |
| Turn-on switching loss                   | $E_{on}$      | $V_{CC} = 600\text{ V}, I_C = 100\text{ A}, R_g = 5.6\text{ }\Omega,$<br>$V_{GE} = \pm 15\text{ V}, L = 200\text{ nH}, T_J = 125\text{ }^\circ\text{C}$ | -    | 4.76 | -    | mJ            |
| Turn-off switching loss                  | $E_{off}$     |   | -    | 4.25 | -    |               |
| Turn-on delay time                       | $t_{d(on)}$   |   | -    | 320  | -    | ns            |
| Rise time                                | $t_r$         |   | -    | 65   | -    |               |
| Turn-off delay time                      | $t_{d(off)}$  |   | -    | 350  | -    |               |
| Fall time                                | $t_f$         |   | -    | 132  | -    |               |
| Turn-on switching loss                   | $E_{on}$      | -   | 7.20 | -    | mJ   |               |
| Turn-off switching loss                  | $E_{off}$     | -   | 5.50 | -    |      |               |
| Short circuit withstand time             | $t_{SC}$      | $T_J = 125\text{ }^\circ\text{C}$   | -    | -    | 10   | $\mu\text{s}$ |
| Input capacitance                        | $C_{ies}$     | $V_{GE} = 0\text{ V}, V_{CE} = 20\text{ V}, f = 1.0\text{ MHz}$   | -    | 8.45 | -    | nF            |
| Output capacitance                       | $C_{oes}$     |   | -    | 0.76 | -    |               |
| Reverse transfer capacitance             | $C_{res}$     |   | -    | 0.31 | -    |               |
| SC data                                  | $I_{SC}$      | $t_p \leq 10\text{ }\mu\text{s}, V_{GE} = \pm 15\text{ V}, V_{CC} = 600\text{ V},$<br>$V_{CEM} \leq 1200\text{ V}, T_J = 25\text{ }^\circ\text{C}$      | -    | 900  | -    |               |
| Internal gate resistance                 | $R_{GINT}$    |   | -    | 2.4  | -    | $\Omega$      |
| Stray inductance                         | $L_{CE}$      |   | -    | -    | 18   | nH            |
| Module lead resistance, terminal to chip | $R_{CC'+EE'}$ |   | -    | 0.32 | -    | m $\Omega$    |



| DIODE ELECTRICAL SPECIFICATIONS     |           |   |                                   |      |      |      |               |
|-------------------------------------|-----------|---|-----------------------------------|------|------|------|---------------|
| PARAMETER                           | SYMBOL    | TEST CONDITIONS   |                                   | MIN. | TYP. | MAX. | UNITS         |
| Diode forward voltage               | $V_F$     | $I_F = 100\text{ A}$  | $T_C = 25\text{ }^\circ\text{C}$  | -    | 1.82 | 2.22 | V             |
|                                     |           |   | $T_C = 125\text{ }^\circ\text{C}$ | -    | 1.95 | -    |               |
| Diode reverse recovery charge       | $Q_{rr}$  | $I_F = 100\text{ A}, V_R = 600\text{ V},$<br>$di_F/dt = -1900\text{ A}/\mu\text{s},$<br>$V_{GE} = -15\text{ V}$ | $T_C = 25\text{ }^\circ\text{C}$  | -    | 5.4  | -    | $\mu\text{C}$ |
|                                     |           |   | $T_C = 125\text{ }^\circ\text{C}$ | -    | 11.2 | -    |               |
| Diode peak reverse recovery current | $I_{rr}$  |   | $T_C = 25\text{ }^\circ\text{C}$  | -    | 81   | -    | A             |
|                                     |           |   | $T_C = 125\text{ }^\circ\text{C}$ | -    | 101  | -    |               |
| Diode reverse recovery energy       | $E_{rec}$ |   | $T_C = 25\text{ }^\circ\text{C}$  | -    | 3.54 | -    | mJ            |
|                                     |           |   | $T_C = 125\text{ }^\circ\text{C}$ | -    | 6.57 | -    |               |

| THERMAL AND MECHANICAL SPECIFICATIONS |            |                           |  |            |       |       |                           |
|---------------------------------------|------------|---------------------------|--|------------|-------|-------|---------------------------|
| PARAMETER                             | SYMBOL     | TEST CONDITIONS           |  | MIN.       | TYP.  | MAX.  | UNITS                     |
| Operating junction temperature range  | $T_J$      |                           |  | - 40       | -     | 150   | $^\circ\text{C}$          |
| Storage temperature range             | $T_{Stg}$  |                           |  | - 40       | -     | 125   |                           |
| Junction to case                      | $R_{thJC}$ | IGBT                      |  | -          | -     | 0.141 | $^\circ\text{C}/\text{W}$ |
|                                       |            | Diode                     |  | -          | -     | 0.225 |                           |
| Case to sink                          | $R_{thCS}$ | Conductive grease applied |  | -          | 0.035 | -     |                           |
| Mounting torque                       |            | Power terminal screw: M6  |  | 2.5 to 5.0 |       |       | Nm                        |
|                                       |            | Mounting screw: M6        |  | 3.0 to 6.0 |       |       |                           |
| Weight                                |            |                           |  | 300        |       |       | g                         |

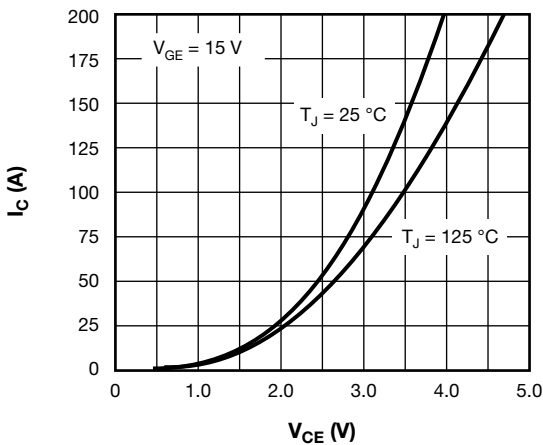


Fig. 1 - IGBT Typical Output Characteristics

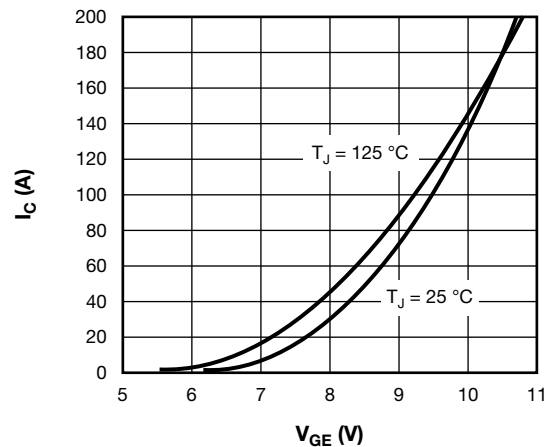


Fig. 2 - IGBT Typical Transfer Characteristics

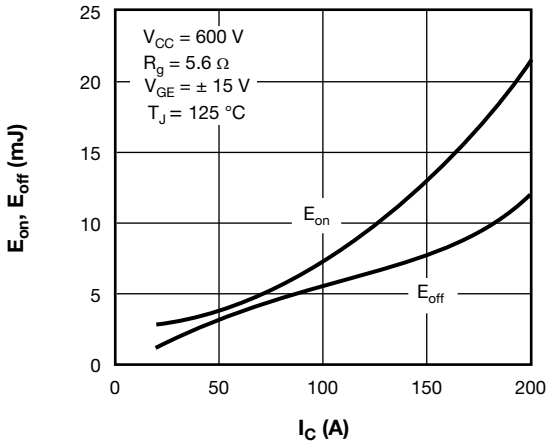


Fig. 3 - Switching Loss vs. I<sub>C</sub>

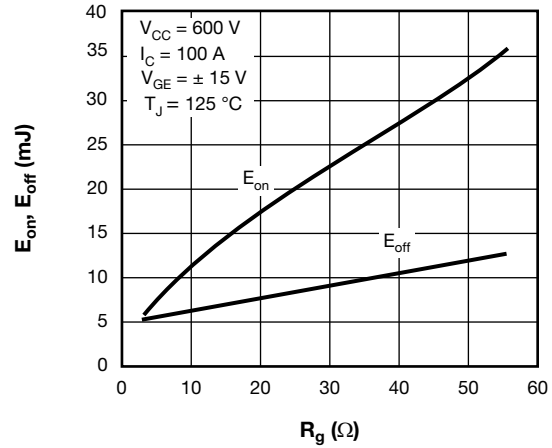


Fig. 4 - IGBT Switching Loss vs. R<sub>g</sub>

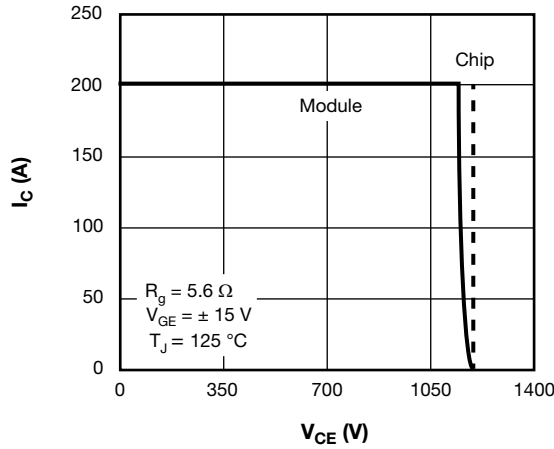


Fig. 5 - RBSOA

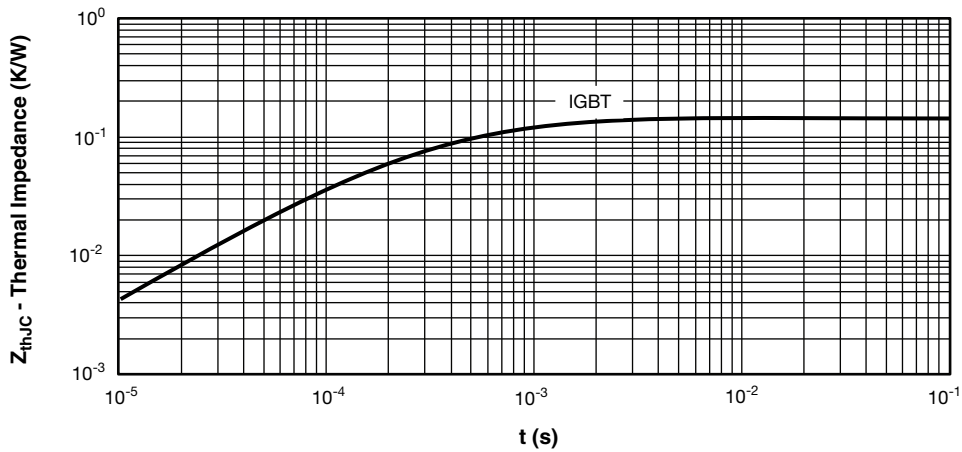


Fig. 6 - IGBT Transient Thermal Impedance

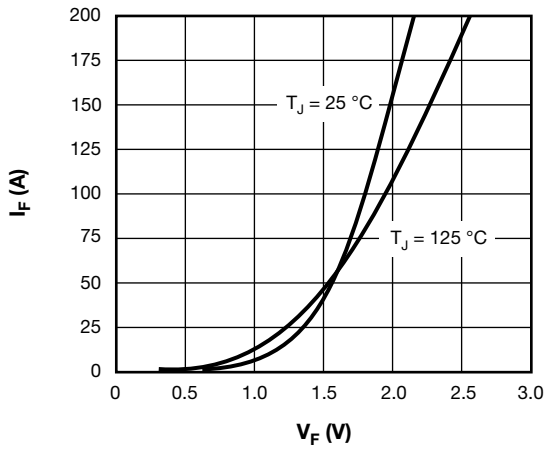


Fig. 7 - Diode Typical Forward Characteristics

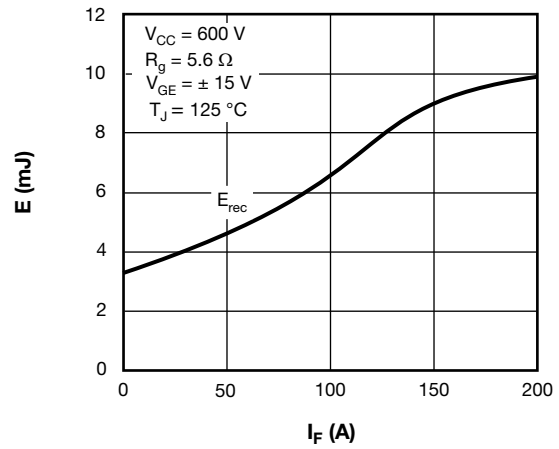


Fig. 8 - Diode Switching Loss vs.  $I_F$

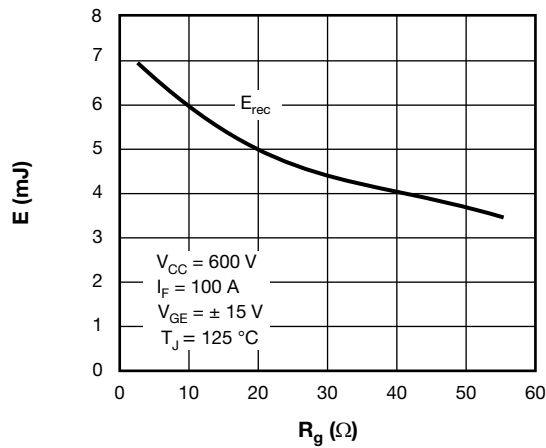


Fig. 9 - Diode Switching Loss vs.  $R_g$

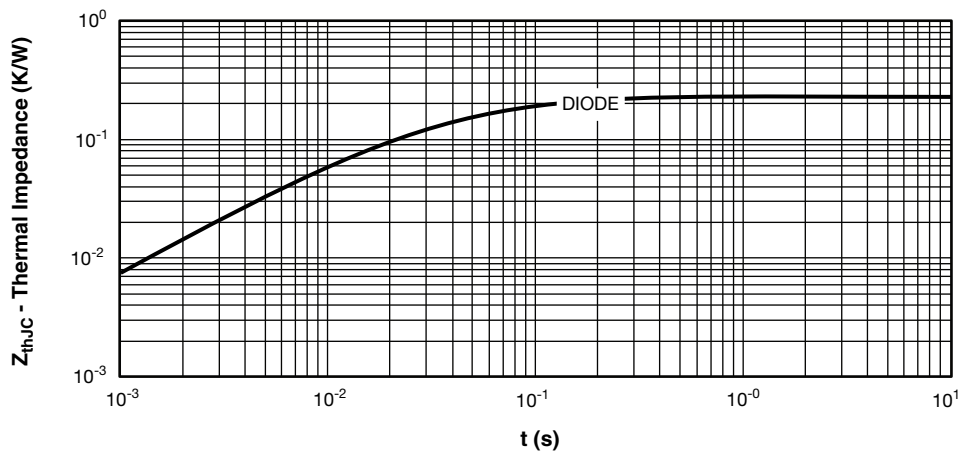
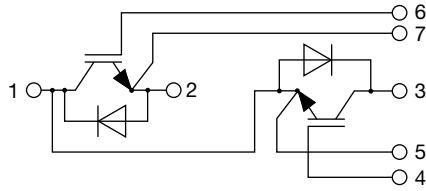


Fig. 10 - Diode Transient Thermal Impedance



**CIRCUIT CONFIGURATION**



**LINKS TO RELATED DOCUMENTS**

|                                   |  |
|-----------------------------------|--|
| <b>LINKS TO RELATED DOCUMENTS</b> |  |
| Dimensions                        | <a href="http://www.vishay.com/doc?95525">www.vishay.com/doc?95525</a> |



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